



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-12
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STC3115UT	EKN5*V788ADJ	A	SH1A	2017-04-12
Amount	UoM	Unit type	ST ECOPACK Grade	
3.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
Not Applicable	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC125)	Tin/Silver/Copper (Sn/Ag/Cu)	N/A		



Package Designator	Size	Nbr of instances	Shape	
BGA	1.4x1.5x0.35	12	bulk solder	
Comment	Package: N5 C5PS0.4 BP 5-16			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 5th August 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel (in trace)	0.0023	bump	767
Lead (in trace)	0.0001	bump	33

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	EKN5*V788ADJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.000	mg	supplier	die	Silicon (Si)	7440-21-3		2.014	mg	671333	671333
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	1667	1667
				supplier	metallization	Copper (Cu)	7440-50-8		0.020	mg	6667	6667
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.005	mg	1667	1667
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	667	667
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	2000	2000
				supplier	Passivation	Silicon Oxide	7631-86-9		0.020	mg	6667	6667
				supplier	polymer die coating	silica vitreous	60676-86-0		0.153	mg	51067	51067
				supplier	polymer die coating	Epoxy resin	25068-38-6		0.055	mg	18333	18333
				supplier	polymer die coating	Acrylic polymer	Proprietary		0.055	mg	18333	18333
				supplier	polymer die coating	Bis-phenol A diglycidyl ether	25036-25-3		0.019	mg	6333	6333
				supplier	polymer die coating	carbon black	1333-86-4		0.002	mg	667	667
				supplier	polymer die coating	chlorine residue	7782-50-5		0.000	mg	33	33
				supplier	polymer die coating	Iron compound	7439-89-6		0.016	mg	5333	5333
				supplier	polymer die coating	Zinc compound	7440-66-6		0.016	mg	5333	5333
				supplier	UBM	Copper (Cu)	7440-50-8		0.002	mg	667	667
				supplier	UBM	Nickel (Ni)	7440-02-0		0.002	mg	667	667
				supplier	bump	Tin (Sn)	7440-31-5		0.597	mg	199000	199000
				supplier	bump	Silver (Ag)	7440-22-4		0.007	mg	2433	2433
				supplier	bump	Copper (Cu)	7440-50-8		0.003	mg	1000	1000
				supplier	bump	Nickel (Ni)	7440-02-0		0.0003	mg	100	100
				JIG - R	bump	Lead (Pb)	7439-92-1		0.0001	mg	33	33